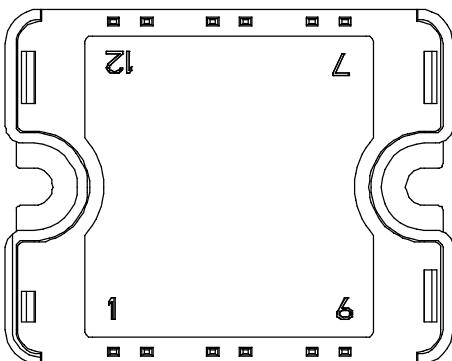
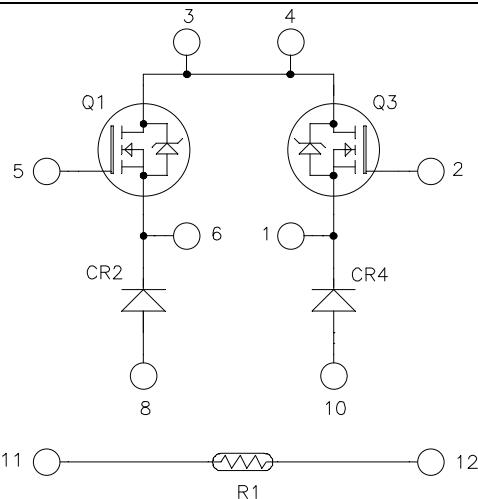


*Dual Buck chopper
Super Junction MOSFET
Power Module*

V_{DSS} = 600V
R_{DSon} = 45mΩ max @ T_j = 25°C
I_D = 49A @ T_c = 25°C



Pins 3/4 must be shorted together

Absolute maximum ratings

Symbol	Parameter	Max ratings	Unit
V _{DSS}	Drain - Source Breakdown Voltage	600	V
I _D	Continuous Drain Current	T _c = 25°C T _c = 80°C	49 38
I _{DM}	Pulsed Drain current		
V _{GS}	Gate - Source Voltage	±20	V
R _{DSon}	Drain - Source ON Resistance	45	mΩ
P _D	Maximum Power Dissipation	T _c = 25°C 250	W
I _{AR}	Avalanche current (repetitive and non repetitive)	15	A
E _{AR}	Repetitive Avalanche Energy	3	mJ
E _{AS}	Single Pulse Avalanche Energy	1900	

 **CAUTION:** These Devices are sensitive to Electrostatic Discharge. Proper Handling Procedures Should Be Followed. See application note APT0502 on www.microsemi.com

All ratings @ $T_j = 25^\circ\text{C}$ unless otherwise specified

Electrical Characteristics

Symbol	Characteristic	Test Conditions		Min	Typ	Max	Unit
I_{DSS}	Zero Gate Voltage Drain Current	$V_{GS} = 0\text{V}$, $V_{DS} = 600\text{V}$	$T_j = 25^\circ\text{C}$			250	μA
		$V_{GS} = 0\text{V}$, $V_{DS} = 600\text{V}$	$T_j = 125^\circ\text{C}$			500	
$R_{DS(on)}$	Drain – Source on Resistance	$V_{GS} = 10\text{V}$, $I_D = 24.5\text{A}$			40	45	$\text{m}\Omega$
$V_{GS(th)}$	Gate Threshold Voltage	$V_{GS} = V_{DS}$, $I_D = 3\text{mA}$		2.1	3	3.9	V
I_{GSS}	Gate – Source Leakage Current	$V_{GS} = \pm 20\text{ V}$, $V_{DS} = 0\text{V}$				100	nA

Dynamic Characteristics

Symbol	Characteristic	Test Conditions		Min	Typ	Max	Unit
C_{iss}	Input Capacitance	$V_{GS} = 0\text{V}$; $V_{DS} = 25\text{V}$ $f = 1\text{MHz}$			7.2		nF
C_{oss}	Output Capacitance				8.5		
Q_g	Total gate Charge	$V_{GS} = 10\text{V}$ $V_{Bus} = 300\text{V}$ $I_D = 49\text{A}$			150		nC
Q_{gs}	Gate – Source Charge				34		
Q_{gd}	Gate – Drain Charge				51		
$T_{d(on)}$	Turn-on Delay Time	Inductive Switching (125°C) $V_{GS} = 10\text{V}$ $V_{Bus} = 400\text{V}$ $I_D = 49\text{A}$ $R_G = 5\Omega$			21		ns
T_r	Rise Time				30		
$T_{d(off)}$	Turn-off Delay Time				100		
T_f	Fall Time				45		
E_{on}	Turn-on Switching Energy	Inductive switching @ 25°C $V_{GS} = 10\text{V}$; $V_{Bus} = 400\text{V}$ $I_D = 49\text{A}$; $R_G = 5\Omega$			675		μJ
E_{off}	Turn-off Switching Energy				520		
E_{on}	Turn-on Switching Energy	Inductive switching @ 125°C $V_{GS} = 10\text{V}$; $V_{Bus} = 400\text{V}$ $I_D = 49\text{A}$; $R_G = 5\Omega$			1100		μJ
E_{off}	Turn-off Switching Energy				635		

Chopper diode ratings and characteristics

Symbol	Characteristic	Test Conditions		Min	Typ	Max	Unit	
V_{RRM}	Maximum Peak Repetitive Reverse Voltage	$V_R = 600\text{V}$		600			V	
I_{RM}	Maximum Reverse Leakage Current		$T_j = 25^\circ\text{C}$			25	μA	
I_F	DC Forward Current		$T_c = 80^\circ\text{C}$		60		A	
V_F	Diode Forward Voltage	$I_F = 60\text{A}$			1.7	2.3	V	
		$I_F = 120\text{A}$			2			
		$I_F = 60\text{A}$	$T_j = 125^\circ\text{C}$		1.4			
t_{rr}	Reverse Recovery Time	$I_F = 60\text{A}$ $V_R = 400\text{V}$ $di/dt = 200\text{A}/\mu\text{s}$	$T_j = 25^\circ\text{C}$		70		ns	
			$T_j = 125^\circ\text{C}$		140			
Q_{rr}	Reverse Recovery Charge		$T_j = 25^\circ\text{C}$		100		nC	
			$T_j = 125^\circ\text{C}$		690			

Thermal and package characteristics

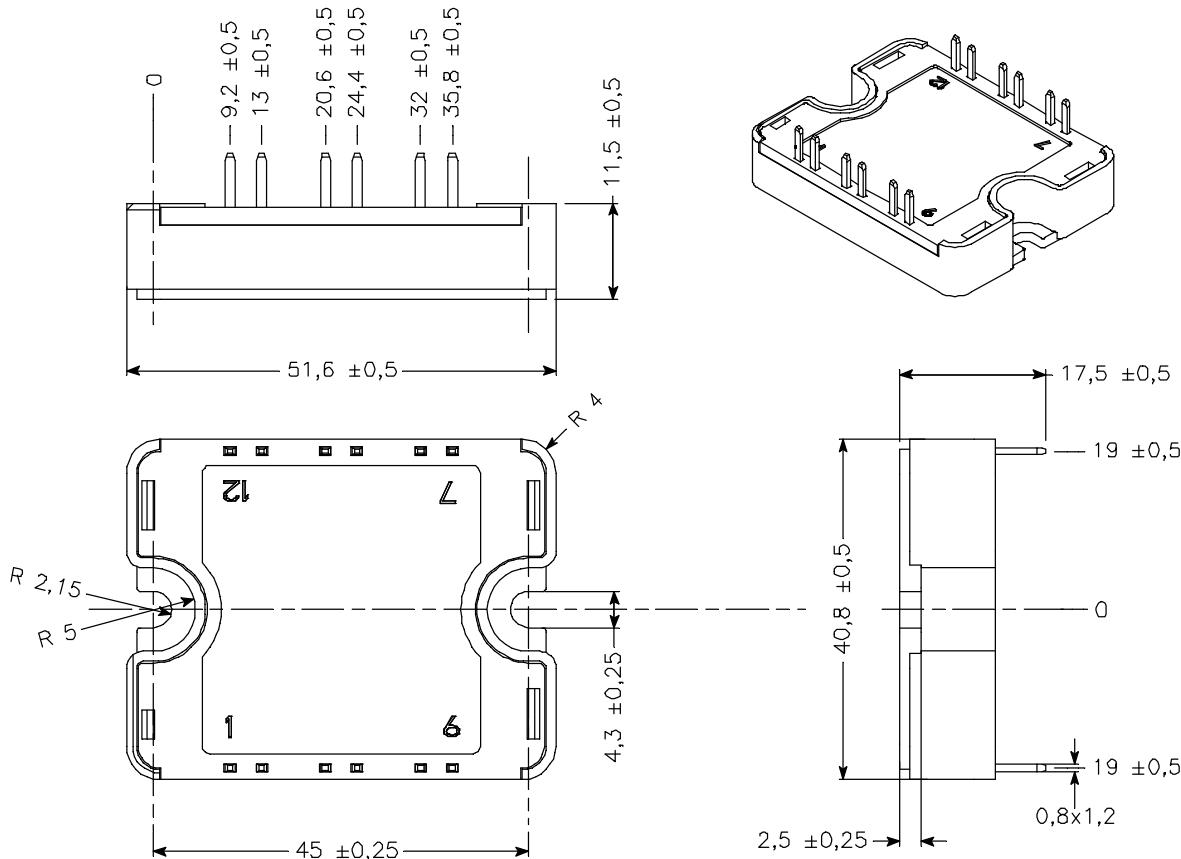
Symbol	Characteristic		Min	Typ	Max	Unit
R_{thJC}	Junction to Case Thermal Resistance	CoolMOS			0.5	°C/W
		Diode			0.85	
V_{ISOL}	RMS Isolation Voltage, any terminal to case t = 1 min, $I_{isol} < 1mA$, 50/60Hz		4000			V
T_J	Operating junction temperature range		-40		150	
T_{STG}	Storage Temperature Range		-40		125	°C
T_C	Operating Case Temperature		-40		100	
Torque	Mounting torque	To heatsink	M4	2.5	4.7	N.m
Wt	Package Weight				80	g

Temperature sensor NTC (see application note APT0406 on www.microsemi.com for more information).

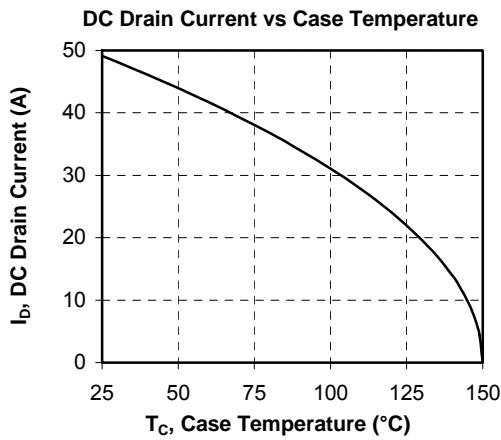
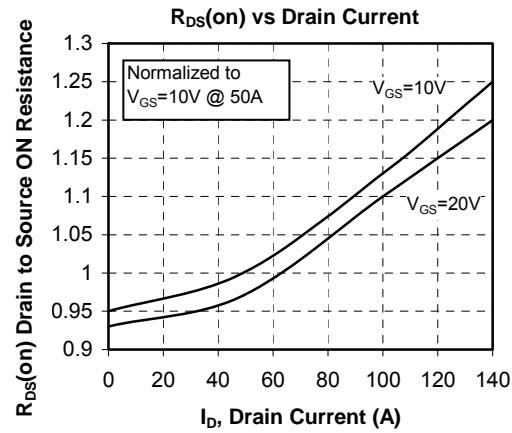
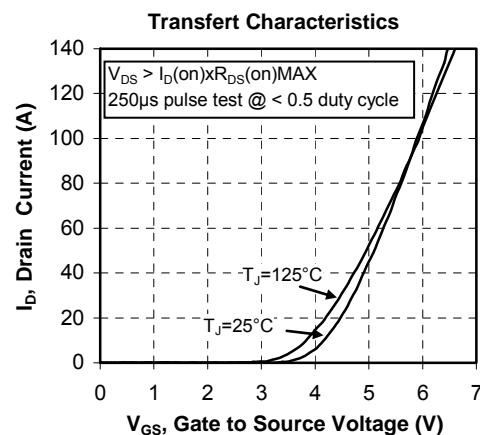
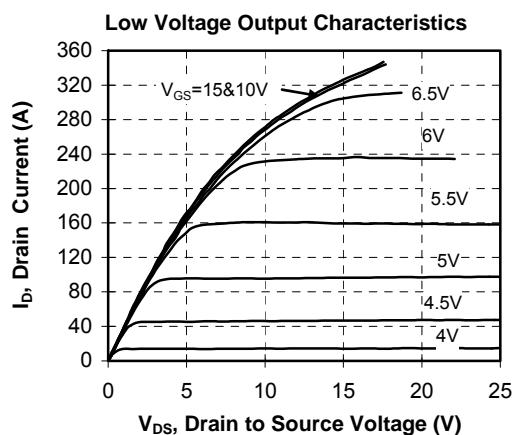
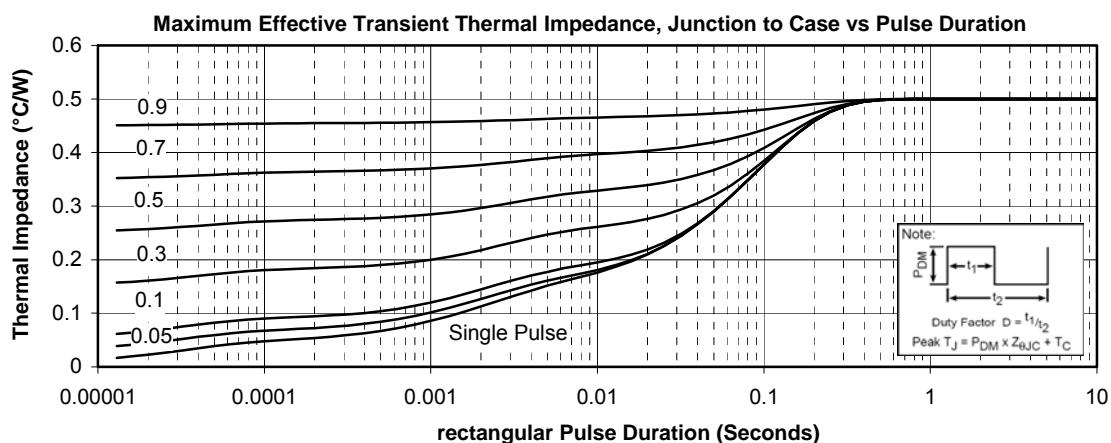
Symbol	Characteristic		Min	Typ	Max	Unit
R_{25}	Resistance @ 25°C			50		kΩ
$\Delta R_{25}/R_{25}$				5		%
$B_{25/85}$	$T_{25} = 298.15 \text{ K}$			3952		K
$\Delta B/B$		$T_C=100^\circ\text{C}$		4		%

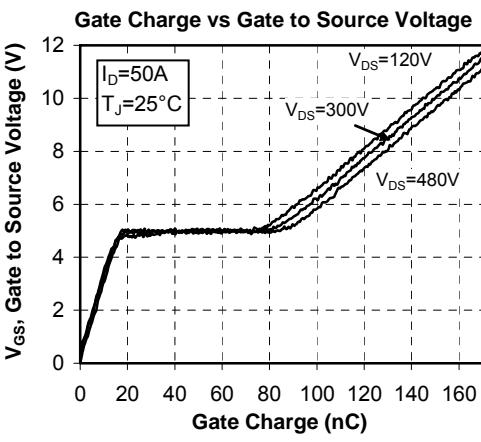
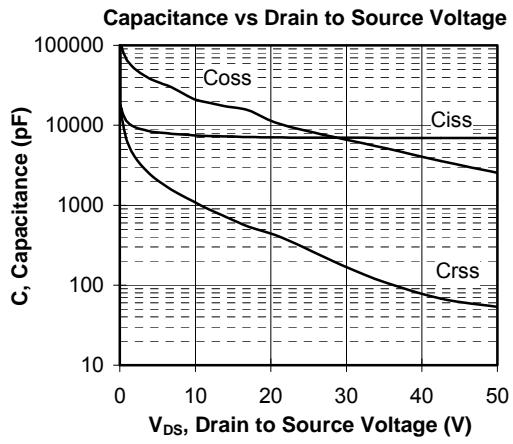
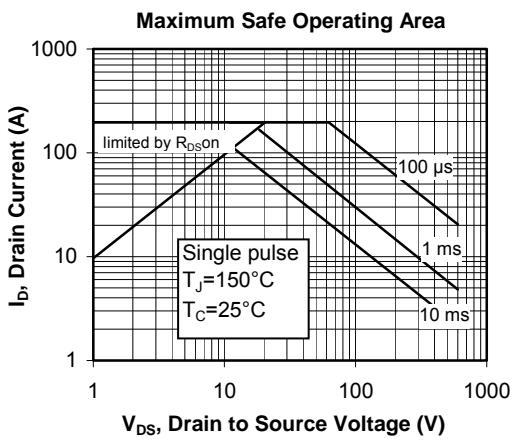
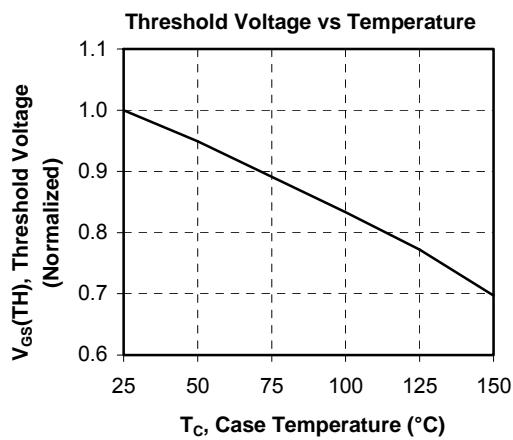
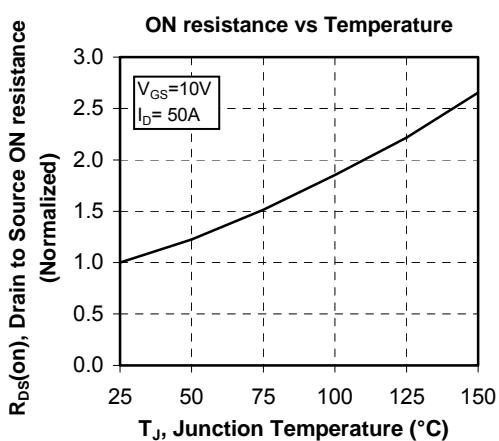
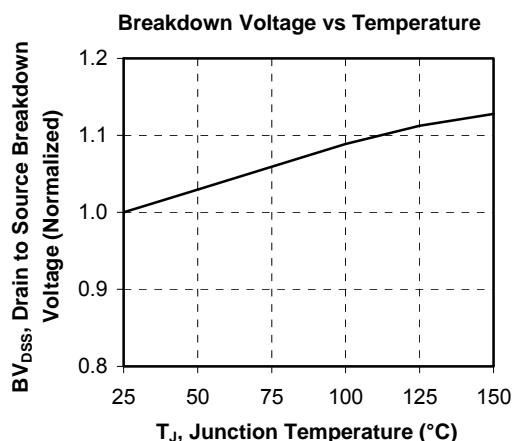
$$R_T = \frac{R_{25}}{\exp\left[B_{25/85}\left(\frac{1}{T_{25}} - \frac{1}{T}\right)\right]}$$

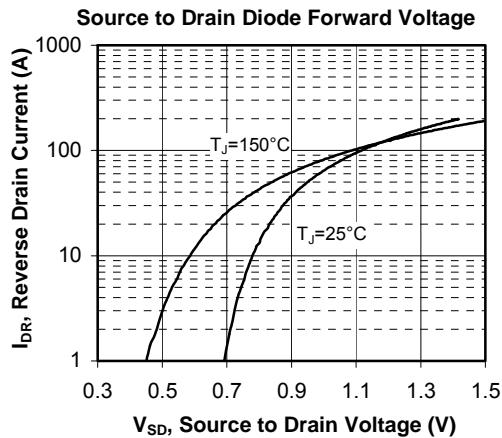
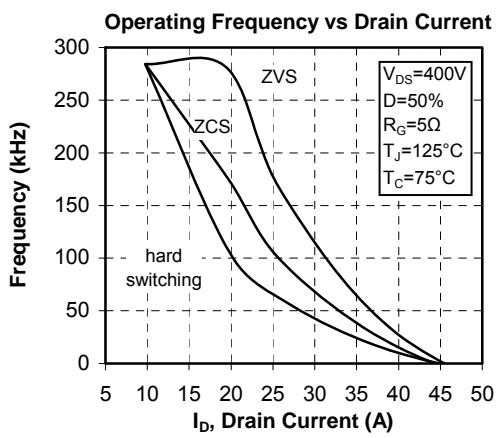
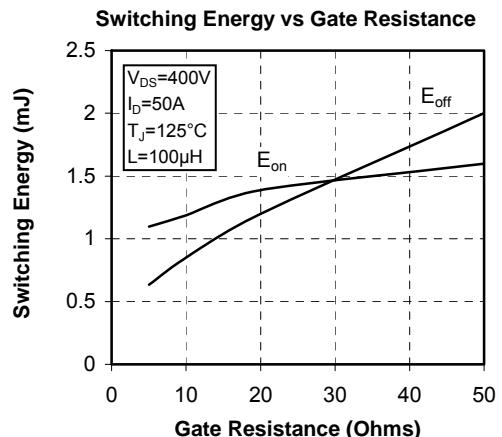
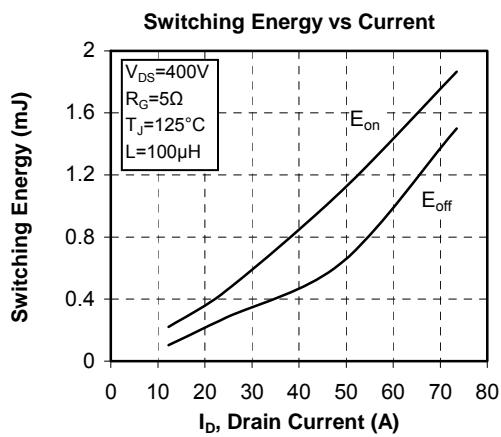
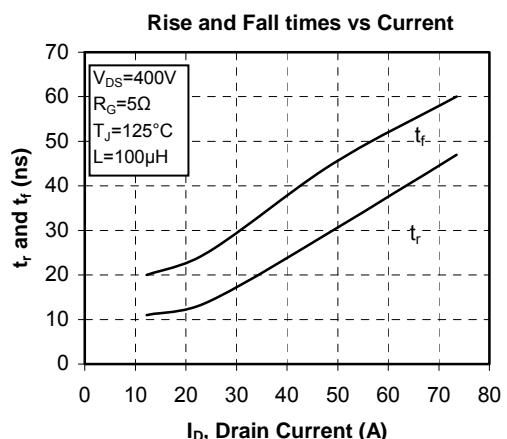
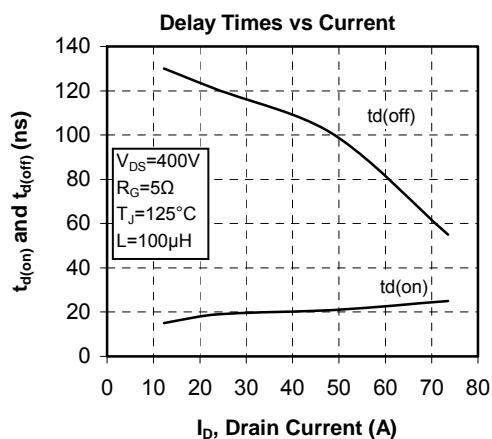
T: Thermistor temperature
R_T: Thermistor value at T

SP1 Package outline (dimensions in mm)

See application note 1904 - Mounting Instructions for SP1 Power Modules on www.microsemi.com

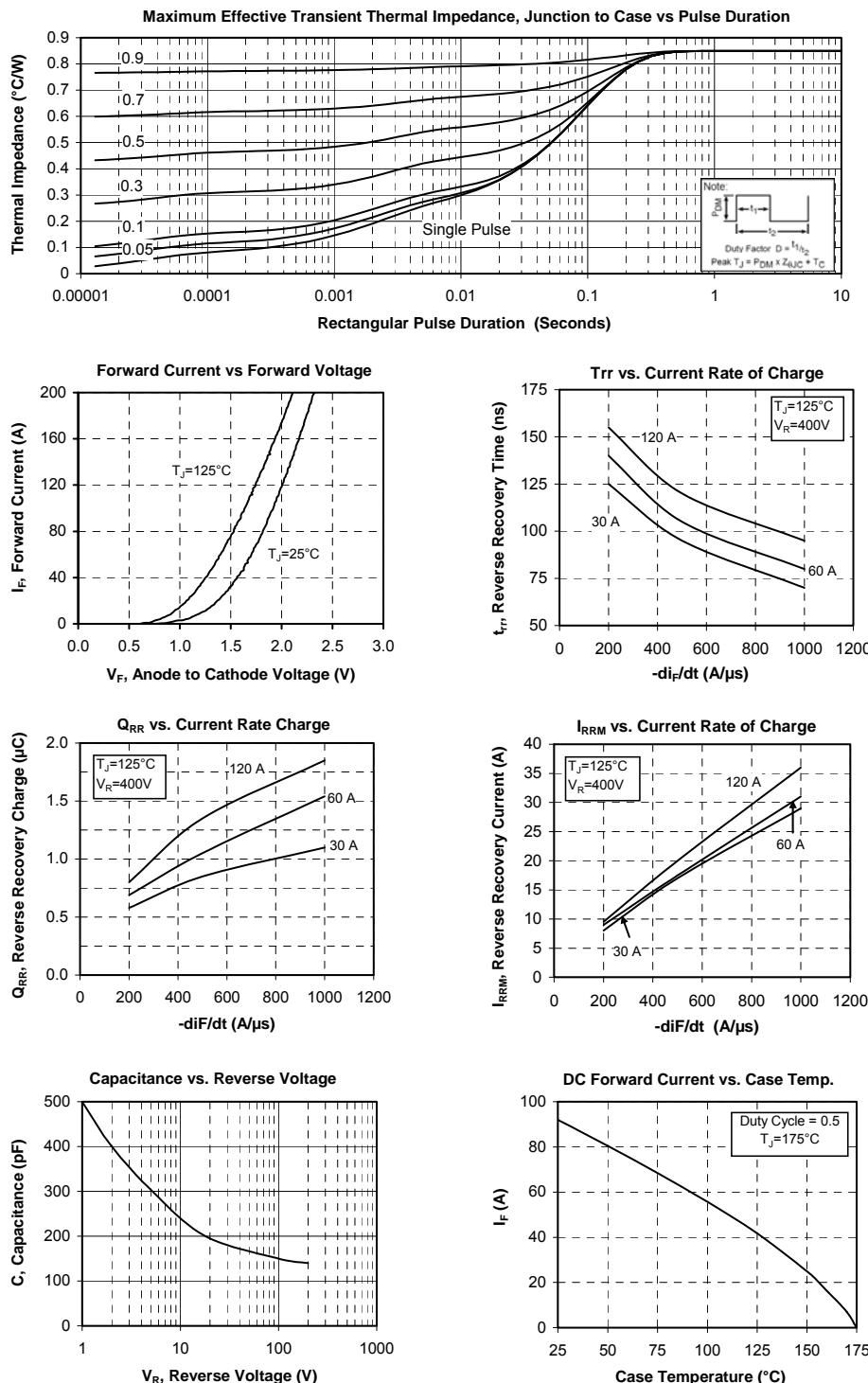
Typical CoolMOS Performance Curve







Typical chopper diode Performance Curve



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